

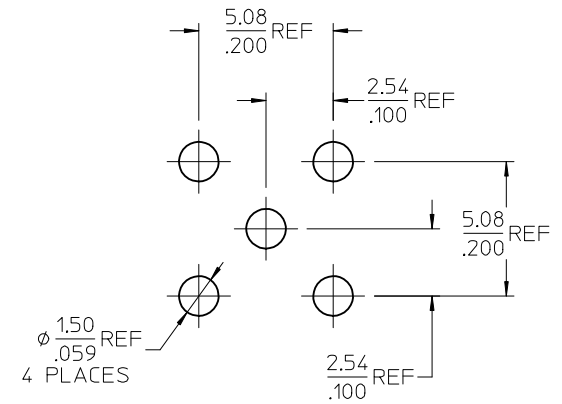
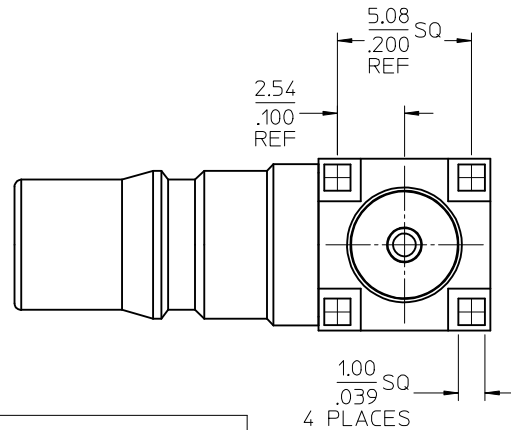
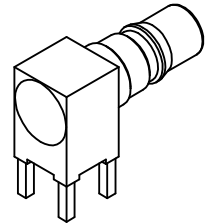
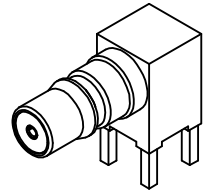
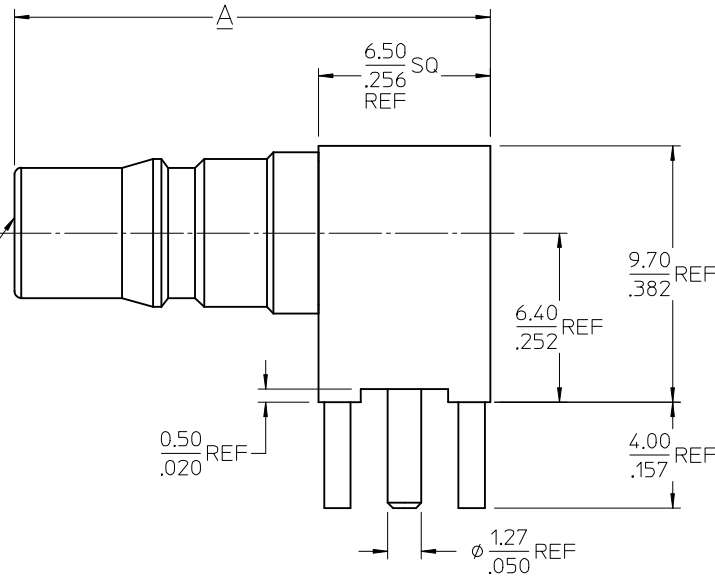
MATERIALS AND FINISHES

BODY, CAP BRASS  
 PLATED GOLD (10 MICROINCHES MIN)  
 OVER CHEMICAL NICKEL

INSULATOR TEFLON

CENTER CONTACT BERYLLIUM COPPER  
 PLATED GOLD (10 MICROINCHES MIN)  
 OVER CHEMICAL NICKEL

QMA JACK  
 INTERFACE



RECOMMENDED PCB  
 LAYOUT

73254-0242	21.00/.827 REF	BAG
73254-0241	18.00/.709 REF	P/N 73254-0240, ONE PER BAG
73254-0240	18.00/.709 REF	TRAY
PART NO.	DIM A	PACKAGING

CHG: UPDATE PACKAGING FOR -0240 & -0242 PER RF15-E217	EC NO: URF2015-0665	2015/05/27
	DRWR:YEH	2015/05/27
CHKD:		
APPR:YCHENG		
REV	DESCRIPTION	
A4		

QUALITY SYMBOLS	▽=0
	▽=0
▽=0	
▽=0	

GENERAL TOLERANCES (UNLESS SPECIFIED)	
mm	INCH
4 PLACES ± .005	± .0004
3 PLACES ± .005	± .0004
2 PLACES ± .005	± .0004
1 PLACE ± .005	± .0004
0 PLACE ± .005	± .0004
ANGULAR ± 2 °	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

DIMENSION STYLE	MM/IN
SCALE	7:1
DESIGN UNITS	METRIC
THIRD ANGLE PROJECTION	
DRAWN BY	DATE
SSS	2005/02/08
CHECKED BY	DATE
TEF	2005/02/08
APPROVED BY	DATE
JDW	2005/02/08
MATERIAL NO.	DOCUMENT NO.
SEE TABLE	SD-73254-024
SIZE	
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QMA JACK, R/A, PCB  
 50 OHMS, EWR2710  
 QMA-J/PCB

**molex**

SHEET NO.  
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